

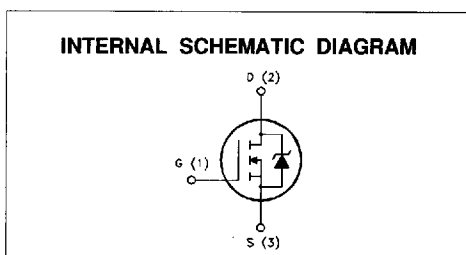
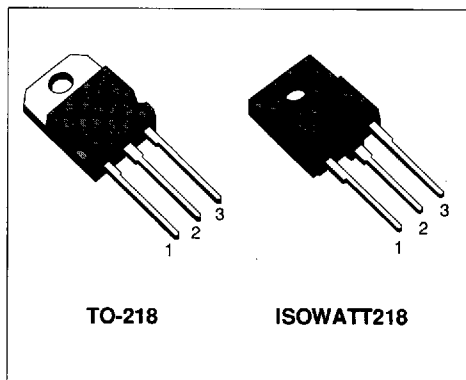
N - CHANNEL ENHANCEMENT MODE POWER MOS TRANSISTOR

TYPE	V _{DSS}	R _{DS(on)}	I _D
STH4N80	800 V	< 3 Ω	4.3 A
STH4N80FI	800 V	< 3 Ω	2.8 A

- TYPICAL R_{DS(on)} = 2.5 Ω
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100°C
- LOW INPUT CAPACITANCE
- LOW GATE CHARGE
- APPLICATION ORIENTED CHARACTERIZATION

APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- CONSUMER AND INDUSTRIAL LIGHTING
- DC-AC INVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLY (UPS)



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		STH4N80	STH4N80FI	
V _{DS}	Drain-source Voltage (V _{GS} = 0)	800		V
V _{DGR}	Drain- gate Voltage (R _{GS} = 20 kΩ)	800		V
V _{GS}	Gate-source Voltage	± 20		V
I _D	Drain Current (continuous) at T _c = 25 °C	4.3	2.8	A
I _D	Drain Current (continuous) at T _c = 100 °C	2.6	1.7	A
I _{DM} (*)	Drain Current (pulsed)	16	16	A
P _{tot}	Total Dissipation at T _c = 25 °C	125	55	W
	Derating Factor	1	0.44	W/°C
V _{ISO}	Insulation Withstand Voltage (DC)	—	4000	V
T _{stg}	Storage Temperature	-65 to 150		°C
T _j	Max. Operating Junction Temperature	150		°C

(*) Pulse width limited by safe operating area

THERMAL DATA

				TO-218	ISOWATT218	
$R_{thj-case}$	Thermal Resistance Junction-case	Max	1	2.27	°C/W	
$R_{thj-amb}$	Thermal Resistance Junction-ambient	Max	30		°C/W	
$R_{thc-sink}$	Thermal Resistance Case-sink	Typ	0.1		°C/W	
T_J	Maximum Lead Temperature For Soldering Purpose			300	°C	

AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I_{AR}	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T_J max, $\delta < 1\%$)	4.3	A
E_{AS}	Single Pulse Avalanche Energy (starting $T_J = 25^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$)	230	mJ
E_{AR}	Repetitive Avalanche Energy (pulse width limited by T_J max, $\delta < 1\%$)	10	mJ
I_{AR}	Avalanche Current, Repetitive or Not-Repetitive ($T_c = 100^\circ\text{C}$, pulse width limited by T_J max, $\delta < 1\%$)	2.6	A

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^\circ\text{C}$ unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown Voltage	$I_D = 250\ \mu\text{A}$ $V_{GS} = 0$	800			V
I_{DSS}	Zero Gate Voltage Drain Current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}$ $V_{DS} = \text{Max Rating} \times 0.8$ $T_c = 125^\circ\text{C}$			250 1000	μA μA
I_{GSS}	Gate-body Leakage Current ($V_{DS} = 0$)	$V_{GS} = \pm 20\text{ V}$			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250\ \mu\text{A}$	2	3	4	V
$R_{DS(on)}$	Static Drain-source On Resistance	$V_{GS} = 10\text{ V}$ $I_D = 1.7\text{ A}$ $V_{GS} = 10\text{ V}$ $I_D = 1.7\text{ A}$ $T_c = 100^\circ\text{C}$		2.5	3 6	Ω Ω
$I_{D(on)}$	On State Drain Current	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $V_{GS} = 10\text{ V}$	4.3			A

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$g_{fs} (*)$	Forward Transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $I_D = 1.7\text{ A}$	1			S
C_{iss}	Input Capacitance	$V_{DS} = 25\text{ V}$ $f = 1\text{ MHz}$ $V_{GS} = 0$			1100	pF
C_{oss}	Output Capacitance				150	pF
C_{rss}	Reverse Transfer Capacitance				55	pF

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Time	$V_{DD} = 30\text{ V}$ $I_D = 2.3\text{ A}$		65	90	ns
t_r	Rise Time	$R_G = 50\ \Omega$ $V_{GS} = 10\text{ V}$ (see test circuit, figure 3)		150	200	ns
$(di/dt)_{on}$	Turn-on Current Slope	$V_{DD} = 600\text{ V}$ $I_D = 3.8\text{ A}$ $R_G = 50\ \Omega$ $V_{GS} = 10\text{ V}$ (see test circuit, figure 5)		80	110	A/ μ s
Q_g	Total Gate Charge	$V_{DD} = 400\text{ V}$ $I_D = 5\text{ A}$ $V_{GS} = 10\text{ V}$		55	70	nC
Q_{gs}	Gate-Source Charge			8		nC
Q_{gd}	Gate-Drain Charge			26		nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_r(V_{off})$	Off-voltage Rise Time	$V_{DD} = 600\text{ V}$ $I_D = 3.8\text{ A}$		110	145	ns
t_f	Fall Time	$R_G = 50\ \Omega$ $V_{GS} = 10\text{ V}$		140	190	ns
t_c	Cross-over Time	(see test circuit, figure 5)		150	200	ns

SOURCE DRAIN DIODE

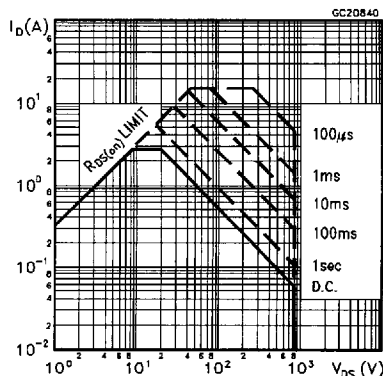
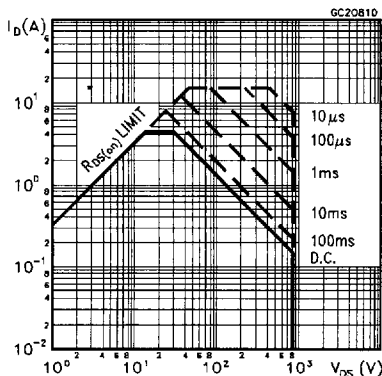
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain Current				4.2	A
$I_{SDM}(\bullet)$	Source-drain Current (pulsed)				16	A
$V_{SD}(\ast)$	Forward On Voltage	$I_{SD} = 4.3\text{ A}$ $V_{GS} = 0$			2	V
t_{rr}	Reverse Recovery Time	$I_{SD} = 3.8\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$ $V_R = 100\text{ V}$ $T_J = 150\text{ }^\circ\text{C}$ (see test circuit, figure 5)		500		ns
Q_{rr}	Reverse Recovery Charge			4.3		μC
I_{RRM}	Reverse Recovery Current			17		A

(*) Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %

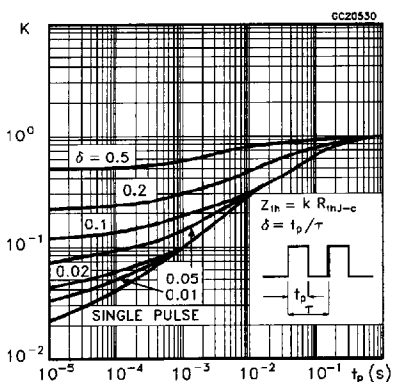
(\bullet) Pulse width limited by safe operating area

Safe Operating Areas For TO-218

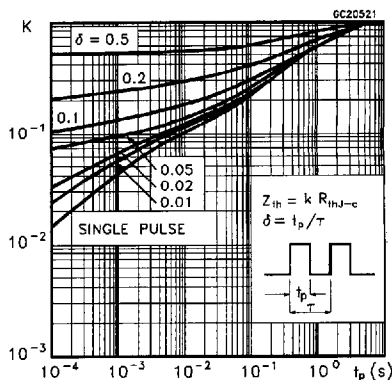
Safe Operating Areas For ISOWATT218



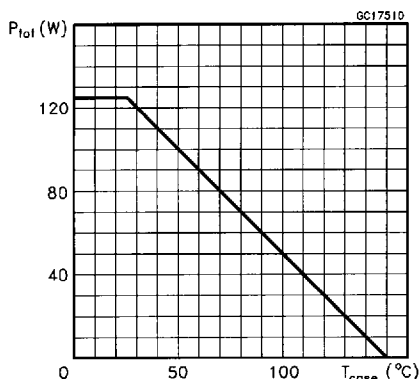
Thermal Impedance For TO-218



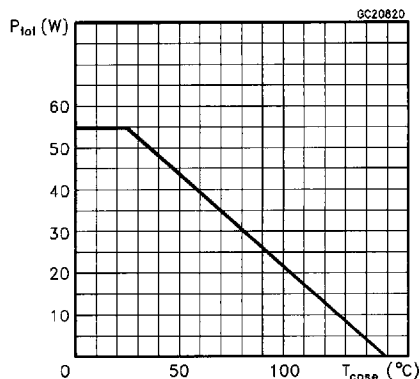
Thermal Impedance For ISOWATT218



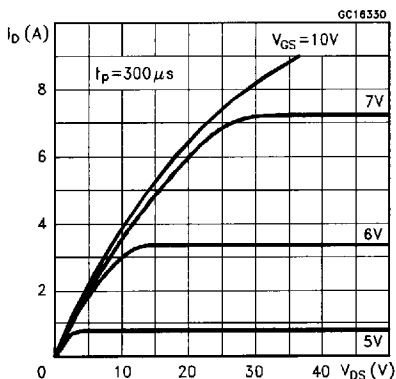
Derating Curve For TO-218



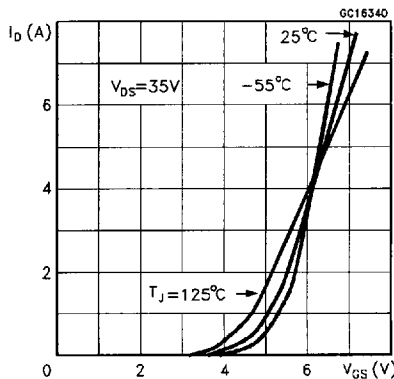
Derating Curve For ISOWATT218



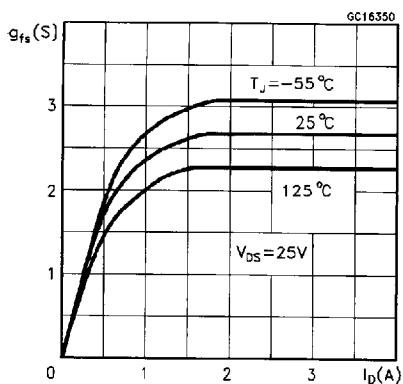
Output Characteristics



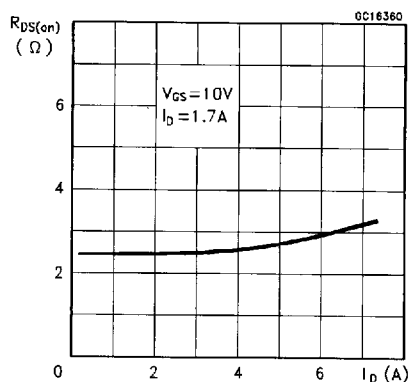
Transfer Characteristics



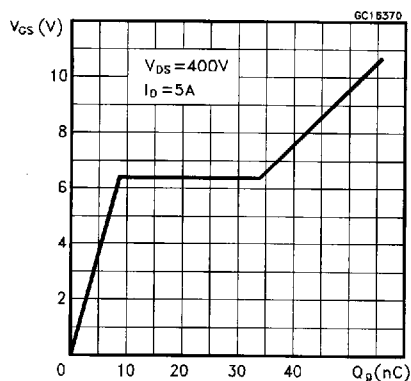
Transconductance



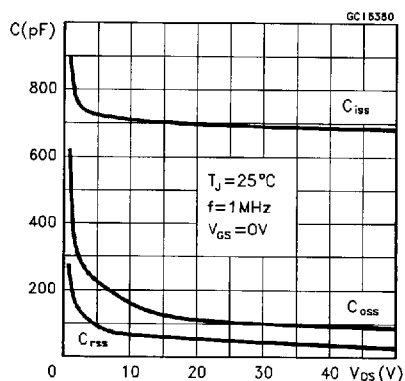
Static Drain-source On Resistance



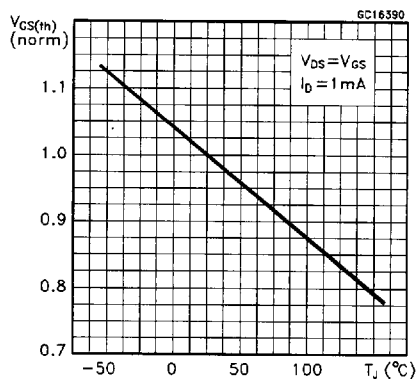
Gate Charge vs Gate-source Voltage



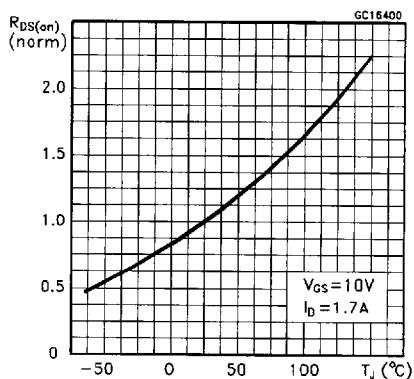
Capacitance Variations



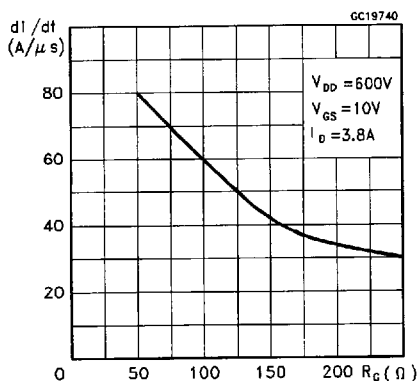
Normalized Gate Threshold Voltage vs Temperature



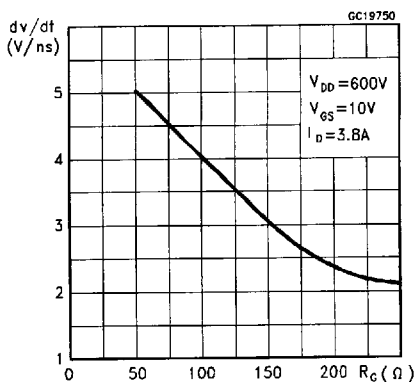
Normalized On Resistance vs Temperature



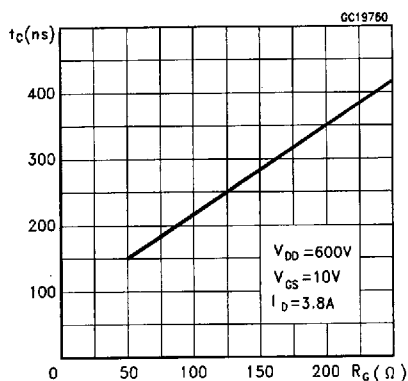
Turn-on Current Slope



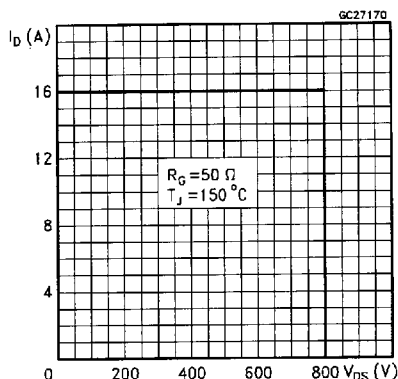
Turn-off Drain-source Voltage Slope



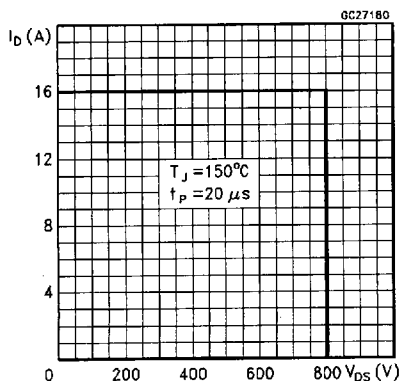
Cross-over Time



Switching Safe Operating Area



Accidental Overload Area



Source-drain Diode Forward Characteristics

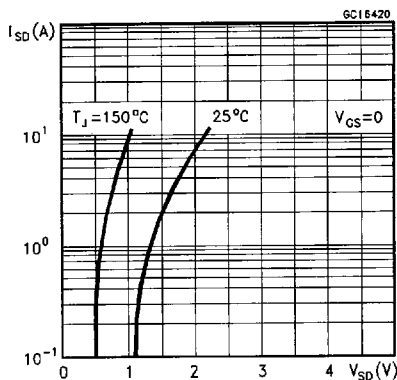


Fig. 1: Unclamped Inductive Load Test Circuits

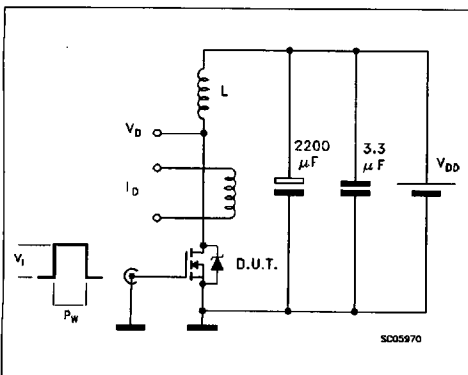


Fig. 2: Unclamped Inductive Waveforms

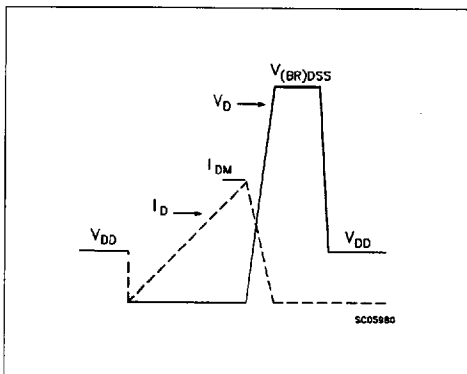


Fig. 3: Switching Times Test Circuits For Resistive Load

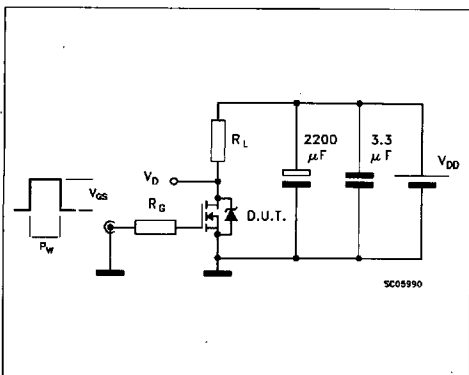


Fig. 4: Gate Charge Test Circuit

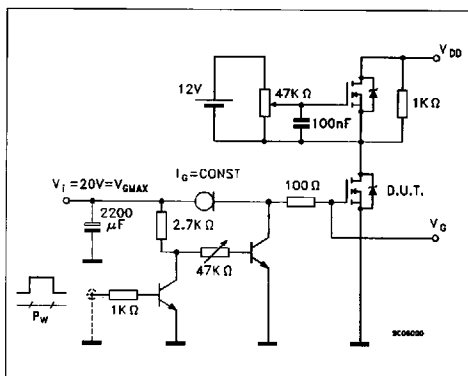


Fig. 5: Test Circuit For Inductive Load Switching And Diode Reverse Recovery Time

